

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
LEE-CHUAN TSENG	09/22/2015
CHANG-MING WU	09/22/2015
SHIH-CHANG LIU	09/22/2015
YUAN-CHIH HSIEH	09/22/2015
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
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Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15850677
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	2015-0439/24061.3168US02
NAME OF SUBMITTER:	JANINE OLINARES
SIGNATURE:	/Janine Olinares/
DATE SIGNED:	12/21/2017
Total Attachments: 3	

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Docket No.: 20150439US0/24061.3168US1

Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|-----------------|----|--|
| (1) | Lee-Chuan Tseng | of | 16F.-2, No. 374, Sec. 1, Wenhua 3 rd Rd., Linkou Dist.
New Taipei City 244, Taiwan, R.O.C. |
| (2) | Chang-Ming Wu | of | No. 16, 327 Ave., Yuan Sun Rd., Chun Ho Div.
New Taipei City, Taiwan, R.O.C. |
| (3) | Shih-Chang Liu | of | No. 21-1, Yuku Village, Kaohsiung County
Alian Township 822, Taiwan, R.O.C. |
| (4) | Yuan-Chih Hsieh | of | 4F., No. 12, Lane 1007, Daxue Rd.
Hsinchu City 300, Taiwan, R.O.C. |

have invented certain improvements in

**METHOD AND APPARATUS FOR REDUCING IN-PROCESS AND IN-USE
STICTION FOR MEMS DEVICES**

for which we have filed an application for Letters Patent of the United States of America on **October 2, 2015**, and assigned U.S. Serial number **14/873,243**; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

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AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Lee-Chuan Tseng

Residence Address: 16F.-2, No. 374, Sec. 1, Wenhua 3rd Rd., Linkou Dist.
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Dated: 2015/9/22

Lee-Chuan Tseng
Inventor Signature

Inventor Name: Chang-Ming Wu

Residence Address: No. 16, 327 Ave., Yuan Sun Rd., Chun Ho Div.
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Dated: 2015/9/22

Chang-Ming Wu
Inventor Signature

Inventor Name: Shih-Chang Liu

Residence Address: No. 21-1, Yuku Village, Kaohsiung County
Alian Township 822, Taiwan, R.O.C.

Dated: 2015/9/22

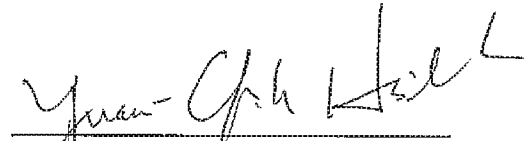
Shih-chang Liu
Inventor Signature

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Customer No.: 42717

Inventor Name: Yuan-Chih Hsieh

Residence Address: 4F., No. 12, Lane 1007, Daxue Rd.
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Dated: 2015. 9. 22


Inventor Signature